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28/2
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Jong Heon KIM]

Serial No.: 10/024,892]

GRP ART UNIT 2812]

Filed: December 18, 2001]

Ex. Lattin, C.W.]

For: METHOD OF FABRICATING A
WAFER LEVEL PACKAGE]

Certification under 37 C.F.R. §1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on September 8, 2003.

Vangelis Economou
Vangelis Economou, Reg. No. 32,341

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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AMENDMENT UNDER 37 C.F.R. § 1.111

Sir:

In response to the Office Action dated June 17, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please substitute the following amended Claims 4, 15 and 27 for the like numbered pending claims. Please cancel Claims 4, 15 and 27 and add new Claim 28.